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M66335FP Facsimile Image Data Processor

REJ03F0276-0200 Rev.2.00 Jun 16, 2008

Description

The M66335 is a facsimile image processing controller to turn into binary signals analog signals which have been output through photo-electric conversion by the image sensor.

The image processing functions includes peak value detection, uniformity correction, resolution change, MTF compensation, γ correction, detection of background/character levels, error diffusion, separation of image zones, and designation of regions.

This controller contains not only the analog processing circuit, the A/D converter of a 7-bit flash type and image processing memory, but also the image sensor and the interface circuit to the CODEC (Coder and Decoder). Therefore, this LSI alone is capable of image processing.

Features

- High speed scan (Max 2 ms/line, Typ 5 ms/line)
- Compatibility with up to the B4 (8 pixels/mm, 16 pixels/mm) image sensor
- Generation of control signals for the image sensor (CCD, CIS) For CCD: SH, CK1, CK2, RS
 - For the contact sensor (CIS): SH, CK1, CK2
- Built-in analog processing circuit (equivalent to the M64291) Sample and hold circuit Gain control circuit Black level clamping circuit Reference internal power supply for the A/D converter
- Built-in A/D converter of a 7-bit flash type
- Built-in image processing memories
 Uniformity correction memory, Line memory, Error memory, γ correction memory
- External output interface for converted binary data Serial output (→ M66330) DMA output
- External output interface for multivalued data DMA transfer of data compensated for uniformity
- Various image processing functions
- Uniformity correction
 - Resolution change from 50% to 200% (by the 1% step)
 - MTF compensation (2-dimensional processing, capable of correction for each character/photo)
- γ correction (capable of correction for each character/photo)
- Detection of background/character levels
- Change to pseudo-halftone
- Error diffusion (64 tone steps through 6-bit processing)
- Organized dither (64 tone steps through the 8×8 matrix)
- Image zone separation (2-dimensional processing)
- 5 V single power supply

Application

Facsimile, word processor and image scanner

Block Diagram



Pin Arrangement



Table 1	Image	Processing	Functions
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Image Processing Functions	Specifications	Remarks
Reading range	• A4, B4	
Resolution	8 pixels/mm, 16 pixels/mm	
	(for the horizontal scanning direction)	
Reading speed	• Typ: 5 ms/line; Max: 2 ms/line	Controlled through the system clock
Uniformity correction	White correction, black correction	Correction memory is built-in
	Correction range: 50%	Readable from/writable in MPU
γ correction	Logarithmic correction	 γ correction memory is built-in
		Capable of correction for each character/photo
MTF compensation	Laplacian filter circuit through 2-	Correction memory is built-in
	dimensional processing	Capable of correction for each character/photo
Simple conversion to binary	Floating slice system through the	
	background/character levels	
Pseudo-halftone	Error diffusion: 6-bit processing (for 64	Error buffer memory is built-in
	tone steps)	• 64 W × 6 bits dither memory is
	• Organized dither: 8 × 8 matrix (for 64 tone steps)	built-in
Image zone separation	2-dimensional processing through luminance difference	
Image reduction	Range of the reduction rate: 50% to	Capable of outputting the average
	100%	line of a dropped line and the
	(by the 1% step)	lines
Image enlargement	Range of the enlargement rate: 100% to 200%	Capable of outputting the average line of a repeated line and the
	(by the 1% step)	subsequent line instead of the
		repeated line
Image sensor control signal	CIS image sensor (clock duty: 75%)	
	CCD image sensor	
Analog processing	The sample/hold circuit, gain control	
	amplifier, black level clamping circuit,	
	and /-bit A/D converter are built-in.	

Pin Description

Sensor SH Output Outputs the shift pulse signal to transfer electric sensor's photoconductor component to its trans interface CCD and the start signal to start the sensor real	charges from the
interface sensor's photoconductor component to its trans	
CCD and the start signal to start the sensor rea	sterring component for
	ding circuit for CIS.
CK1 Output Outputs the clock pulse signal to sequentially tr	ansfer out signaling
electric charges from the sensor's transferring of	component for CCD and
the clock pulse signal for the shift register of the	e sensor reading circuit for
CK2 Output Reversed-phase pulses of CK1	
RS Output Outputs the reset pulse to return the voltage at the CCD sensor to the initial one.	the floating capacitor of
PTIM Output Outputs the pulse motor control signal for the re	eading roller.
CODEC SRDY Input Transfer start ready signal for data from CODE	C
interface STIM Output Defines the data transfer section to CODEC	-
SCLK Output Clock signal to transfer image data to CODEC	
SVID Output Output Outputs image data in serial to CODEC	
DMA DBO Output DMA request signal to the external DMA control	ller to output in parallel
interface	nor to output in parallor
DAK Input DMA acknowledge signal from the external DM	A controller in response to
the above DRQ signal	•
INT Output Single-line termination interrupt	
Clock SYSCK Input System clock input pin	
ACCK Output Single-line cycle clock	
MPU RESET Input Input of the system reset. The cycle counter, re	gister, F/F, and latch are
interface reset.	
CS Input Chip select signal for MPU to access the M663	35
RD Input Control signal for MPU to read data from the M	66335
WR Input Control signal for MPU to write data to the M66	335
A0 to A4 Input Address signal to access various registers insid	le the M66335
D0 to D7 Input/Output 8-bit two way buffer	
Others V _{CC} — Positive power supply pin	
GND — GND pin	
TESTI, 0 to 6 Input Test input pin. Hold this at "L".	
TESTO Output Test output pin. Set this open.	
Power AV _{CC} — Analog power supply pin (rated supply voltage:	5 V)
supply DV _{CC} — Digital power supply pin (rated supply voltage: 5	5 V)
GND AGND — Analog ground pin	
DGND — Digital ground pin	
Sensor AIN Input Pin to input analog signals output from CCD or	CIS (Signals from CCD
signal are input through capacity coupling and those fi	rom CIS, with no
input part clamping levels, are input directly.)	
Gain C1, C2 Input Pin to control the frequency characteristic of the	e gain control circuit
control LEVAJ Input Pin to control the DC level of output signals of t	he gain control circuit.
The output voltage, V _{GCAO} , is obtained by the fo	ollowing equation:
$V_{GCAO} = V_{LEVAJ} + G_V \times V_{IN},$	
where,	
V _{LEVAJ} : voltage at LEVAJ	
V _{IN} : input signal	
G _V : gain of the gain control circuit	
$v_{\rm IN}$ is the signal element corresponding to the s	S3 input or to the CND
level for CIS1 • CIS2 input	
GCAO Output Signal output nin of the gain control circuit	

Pin Description (cont.)

Item	Pin Name	Input/Output	Function
Black level clamping	BCMI	Input	Signal input pin to the black clamping circuit. Use this with capacity coupling with the GCAO pin.
circuit	BCMV	Input	Pin to set the black level clamping voltage. Sets the black level of signals output from the BCMO pin for CCD signal processing.
	BCMO	Output	Signal output pin of the black level clamping circuit
A/D converter	Vri+	Input	Output of the circuit to generate the A/D full-scale point reference voltage (3.8 V). Connected with VWL through the buffer inside the IC. To change the A/D reference voltage range, input a DC voltage from this pin.
	Vri–	Input	Output of the circuit to generate the A/D zero point reference voltage (1.8 V). Connected with VBL through the buffer inside the IC. To change the A/D reference voltage range, input a DC voltage from this pin.
	ADIN	Input	Signal input pin to the A/D converting circuit. Use this by connecting with the BCMO pin for CCD or with the GCAO pin for CIS. Input signals in the voltage range (1.8 V to 3.8 V) set through VWL and VBL.
	VWL	Output	Output of the circuit generating the A/D full-scale reference voltage (3.8 V). Connected inside the IC with the A/D converter.
	VBL	Output	Output of the circuit generating the A/D zero point reference voltage (1.8 V). Connected inside the IC with the A/D converter.

Absolute Maximum Ratings

 $(Ta = -20 \text{ to } +75^{\circ}\text{C}, \text{ unless otherwise noted})$

Item	Symbol	Ratings	Unit
Supply voltage	V _{CC}	-0.3 to +6.5	V
Input voltage	VI	–0.3 to V _{CC} + 0.3	V
Output voltage	Vo	0 to V _{CC}	V
Analog supply voltage	AV _{CC}	$V_{CC} - 0.3$ to $V_{CC} + 0.3$	V
Supply voltage	DV _{CC}	$V_{CC} - 0.3$ to $V_{CC} + 0.3$	V
Reference voltage (white)	V _{WL}	-0.3 to AV _{CC} + 0.3	V
Reference voltage (black)	V _{BL}	-0.3 to AV _{CC} + 0.3	V
Analog input voltage	V _{AIN}	-0.3 to AV _{CC} + 0.3	V
Storage temperature	Tstg	-55 to +150	C

Recommended Operational Conditions

Item	Symbol	Min	Тур	Max	Unit
Supply voltage (for the digital system component)	V _{CC}	4.75	5.0	5.25	V
GND voltage	GND	_	0.0	_	V
Input voltage	VI	0	_	V _{CC}	V
Analog supply voltage	AV _{CC}	4.75	5.0	5.25	V
Analog GND voltage	A _{GND}	_	0.0	_	V
Supply voltage (for the digital system component)	DV _{CC}	4.75	5.0	5.25	V
GND voltage	D _{GND}	_	0.0	_	V
Input range: $V_{WL} \le AV_{CC}$; $V_{BL} \ge A_{GND}$	V _{AIN}	1.8	2.0	2.2	Vp-p
Operating temperature	Topr	-20	_	+75	°C

Note: Connect the analog system component and the digital system component separately to power supply on the evaluation board for noise prevention.

Electrical Characteristics

$(Ta = -20 \text{ to } +75^{\circ}\text{C}, V_{CC} = 5 \text{ V} \pm 5\%, \text{ unless otherwise noted})$						
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
"H" input voltage	V _{IH}	2.0			V	
"L" input voltage	VIL	—		0.8	V	
Positive direction input threshold	VT+	—		2.4	V	
Negative direction input threshold	VT–	0.6			V	
Hysteresis value	V _H	—	0.2		V	
"H" output voltage	V _{OH}	$V_{CC} - 0.8$			V	$I_{OH} = -12 \text{ mA}$
"L" output voltage	V _{OL}	—		0.55	V	I _{OL} = 12 mA
"H" output voltage	V _{OH}	$V_{CC} - 0.8$			V	$I_{OH} = -4 \text{ mA}$
"L" output voltage	V _{OL}	—		0.55	V	$I_{OL} = 4 \text{ mA}$
"H" input current	Іін			1.0	m۸	$V_{CC} = 5.25 V$
				1.0		V _I = 5.25 V
"L" input current	IIL	_	_	-1.0	mA	$V_{CC} = 5.25 V$
						$V_I = 0 V$
"H" input current in the off state	I _{OZH}	_	_	5.0	mA	$V_{CC} = 5.25 V$
						V _O = 5.25 V
"L" input current in the off state	I _{OZL}	_	_	-5.0	mA	$V_{CC} = 5.25 V$
						$V_{\rm O} = 0 V$
Analog input current	I _{AIN}	—		1.0	mA	
Reference resistance	R_L	—	120	_	Ω	
Differential non-linear error	Ed	—	±1.0	—	LSB	
Static current dissipation	I _{CCS}		01	25	m۸	$V_{CC} = 5.25 V$
(during standby)			21	30	IIIA	$V_{I} = V_{CC}, GND$

Timing Conditions

		(1a = -20 to + 75	$^{-}C, V_{CC} = 5 V =$	= 5%, unless our	ierwise noted)
ltem		Symbol	Min	Тур	Max	Unit
System clock cycle		t _{c (SYS)}	50	_		ns
System clock "H" pulse wid	dth	t _{w+ (SYS)}	25	_		ns
System clock "L" pulse wic	lth	t _{w- (SYS)}	25	_	_	ns
System clock rise time		t _{r (SYS)}	—	_	20	ns
System clock fall time		t _{f (SYS)}	—	_	20	ns
Read pulse width		t _{w (RD)}	100	_	_	ns
Set-up time before read	CS	t _{su (CS-RD)}	20	_	_	ns
Set-up time before read	A0 to A4	t _{su (A-RD)}	20	_	_	ns
Set-up time before read	DAK	t _{su (DAK} -RD)	20	_	_	ns
Hold time after read	CS	t _{h (RD} -CS)	10	_	_	ns
Hold time after read	A0 to A4	t _{h (RD-A)}	10	_	_	ns
Hold time after read	DAK	t _{h (RD} -DAK)	10	_	_	ns
Write pulse width		t _{w (WR)}	100	_	_	ns
Set-up time before write	CS	t _{su (CS} -WR)	20	—	_	ns
Set-up time before write	A0 to A4	t _{su (A-WR)}	20	—	_	ns
Set-up time before write	D0 to D7	t _{su (D-WR)}	50	—	_	ns
Hold time after write	CS	$t_{h} (\overline{WR} \cdot \overline{CS})$	20	—	_	ns
Hold time after write	A0 to A4	t _{h (WR-A)}	10			ns
Hold time after write	D0 to D7	t _{h (WR} -D)	0	—	—	ns
Hold time after STIM	SRDY	th (STIM-SBDY)	0	_	_	ns

(Ta = -20 to $+75^{\circ}$ C, V_{CC} = 5 V \pm 5%, unless otherwise noted)

Switching Characteristics

		(Ta = -	$-20 \text{ to } +75^{\circ}\text{C}$	$C, V_{CC} = 5 V$	$7 \pm 5\%$, unle	ess otherwise noted)
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Enable time for data output	t _{PZL (RD} -D)			75	ns	C _L = 150 pF
after read	t _{PZH (RD} -D)				ns	
Disable time for data output	t _{PLZ} (RD-D)	10		50	ns	
after read	t _{PHZ} (RD-D)				ns	
Propagation time of DRO output after read	tphl (RD-DRO)			50	ns	C _L = 50 pF

Test Circuit



Item	SW1	SW2
t _{PLH} , t _{PHL}	Open	Open
t _{PLZ}	Closed	Open
t _{PHZ}	Closed	Closed
t _{PZL}	Closed	Open
t _{PZH}	Open	Closed

(1) Characteristics (10% to 90%) of the pulse generator (PG): t_{r} = 3 ns; t_{f} = 3 ns

(2) Capacitance C_L (= 150 pF) includes the stray capacitance of connections and input capacitance of the probe.

System Clock



(1) Operation Mode

The M66335 has three basic operations.

- Peak value detection: Adjusting the peak value of analog signals output from the analog circuit to the white reference voltage (VWL) of the A/D converter built in the M66335.
- Generation of data for uniformity correction: Generating data on a white reference original sheet for uniformity correction by the sensor unit and writing them to the memory for correction built-in the M66335.
- Read: Reading original sheets, performing image processing of the read image data, and outputting in serial or parallel the indicated converted binary data.

The M66335 is capable of performing the DMA transfer of multivalued data (6-bit data = D7 to D2, D1 = D0 = 0) after correction about uniformities.

These three basic operations are performed in the following mode sequences for the CCD sensor and CIS sensor. The sensor is set through the register 00 (SENS).

For the CCD Sensor



For the CIS Sensor



The peak value of the 16 line cycle is detected by setting the AGC command in the register 00 at "H".

To escape this mode, set the AGC command at "L" after a 20 line cycle (or a cycle of 16 lines or more) passed since the start.

This operation mode is started by setting the UNIF command in the register 00 at "H" after setting UMODE: "H" (white correction) in the register 00 and UNIFM: "L" (only white correction) in the register 01.

Starting by the UNIF command also makes the system generate data for nonuniformity correction for white correction (for the 8 line cycle).

To escape this mode, set the UNIF command at "L" after a 10 line cycle (or a cycle of 8 lines or more) passed since the start.

The read operation mode is started by setting the SCAN command in the register 00 at "H". To escape this mode, set the SCAN command at "L".

The peak value of the 16 line cycle is detected by setting the AGC command in the register 00 at "H".

To escape this mode, set the AGC command at "L" after a 20 line cycle (or a cycle of 16 lines or more) passed since the start.

When this operation mode is started by the UNIF command after setting UMODE: "L" (black correction) in the register 00 and UNIFM: "H" (black and white correction) in the register 01, the system also generates black data for non-uniformity correction for black correction (for the 8 line cycle).

To escape this mode, set the UNIF command at "L" after a 10 line cycle (or a cycle of 8 lines or more) passed since the start.

In the case of only white correction, the setting is not necessary. Follow the instruction below.

When this operation mode is started by the UNIF command in the register 00 after setting UMODE: "H" (white correction) in the register 00 and UNIFM: "L" (only white correction) in the register 01, the system also generates white data for non-uniformity correction for white correction (for the 8 line cycle).

To escape this mode, set the UNIF command at "L" after a 10 line cycle (or a cycle of 8 lines or more) passed since the start.

The reading operation is started by setting the SCAN command in the register 00 at "H". To escape this mode, set the SCAN mode at "L".

The signal operations and data flow in each basic operation are shown in the page 9 and 10, and the flowchart is in the page 26 and 27.

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Operations of Signals in the Peak Value Detection Operation



Flow of Data in the Creation of Data for Uniformity Correction





Flow of Data in the Reading Operation (for Output in Serial: Binary Data)





Flow of Signals in the Reading Operation (for Multivated Data)



(2) Line Cycle and Reading Sequence

The relationship between the line cycle and the reading sequence of the M66335 is shown in figure 1.

The relationship between the CODEC interface operations and the reading sequence is shown in figure 2 and that between the DMA interface operations and the reading sequence is shown in figure 3.

- Single-line cycle (1/ACCK)
 - Defines the processing time per line of the M66335.

The single-line cycle is decided by the line cycle counter value registers 03 and 04 (PRE_DATA), and the pixel transfer clock.

The pixel transfer clock is 1/16 of SYSCK.

1 line cycle (1/ACCK) [NS]

- = line cycle counter value × pixel transfer clock cycle [NS]
- = $(PRE_DATA + 1) \times pixel transfer clock cycle [NS]$
- = (PRE_DATA + 1) × 16/SYSCK [NS]

After loading the PRE_DATA value, the line cycle counter generates the addresses of the following gate signals while counting down with the pixel transfer clock.

• Sensor start pulse (SH)

Image sensor start pulse. The point of the start pulse is decided by the uniformity correction range (UNIFG) and the value of the register 05.

[ST_PL]

The ST_PL value must be set according to the following formulas for each image sensor type. CCD: ST PL = dummy pixels of the sensor + 2

CIS: ST PL = 2

• Uniformity correction range (UNIFG)

Defines the range where uniformity correction is performed. This range corresponds to the width of the sensor (B4 to A4).

For the relationship between the sensor width and the uniformity correction range, see table 2.

• AGC range (AGCG)

Defines the range where peak value detection is performed. This range corresponds to the sensor width (B4 to A4). Auto gain control is performed for the whole width of the sensor (solid line) in the AGC mode and for the narrower width (dashed line) than the sensor width in the SCAN mode.

For the relationship between the sensor width and the AGC range, see table 2.

• Original sheet reading width

Defines the reading width for original sheets.

For original sheet widths narrower than the sensor width, the reading range (dashed line) is set, using the sensor center as the base center point. Therefore, the points for the original sheet should be based on the sensor center. For the relationship between the sensor width and the original sheet reading width, see table 3.

• Pulse motor control signal ($\overline{\text{PTIM}}$)

Generates control signals for the pulse motor for the reading roller.







Figure 2 CODEC Interface Operations and the Reading Sequence (Binary Data Output: Serial Output)



Figure 3 DMA Interface Operations and the Reading Sequence (Multivated Data Output)

Table 2 Gate Signal Ranges for the Sensor Widths

	Sensor Width			
Gate Signal		Resolution	B4	A4
Uniformity correction range (UNIFG)		200 dpi	2103/55	1943/215
		400 dpi	4207/111	3887/431
AGC range (AGCG)	AGC mode	200 dpi	2103/55	1943/215
		400 dpi	4207/111	3887/431
	SCAN mode	200 dpi	2018/130	1584/564
		400 dpi	4037/261	3169/1129

Table 3 Original Sheet Reading Widths According to the Original Sheet Widths for the Sensor Widths

Sensor Width			
Original Sheet Width	Resolution	B4	A4
B4	200 dpi	2102/54	_
	400 dpi	4206/110	
A4	200 dpi	2102/54	1942/214
	400 dpi	4206/110	3886/430

When original sheets narrower than the sensor width, cut out the original sheet width with the registers 11 to 14. (OFFSET, OUTLENGTH): (Region designation function)

X/Y	Х	Y	
X: Left end address			
Y: Right end address			

(3) Image Processing Function

The M66335 converts image signals input from the image sensor into binary data. This includes the simple conversion of characters and the change of images with various densities into pseudo-half-tone.

Before the conversion, distortions and characteristic degradations which signals from the image sensor almost always have must be corrected or compensated.

Image zone separation must also be performed to realize optimal conversion-to-binary of the image for the possible shortest transmission time.

Functions required for image processing are as follows.

- Peak value detection
- Uniformity correction
- Resolution change (enlargement, reduction and averaging)
- MTF compensation
- γ correction
- Background/character level detection (simple conversion to binary)
- Change to pseudo-halftone

Organized dither Error diffusion

- Image zone separation
- Designation of regions

Peak Value Detection

Because the A/D converter of the M66335 uses the input dynamic range at 2 Vp-p, the reference voltages (V_{WL} , V_{BL}) corresponding to the peak value are fixed. The peak value of analog signals output from the analog processing circuit must be detected before those signals are input to the A/D converter in order to adjust the analog signal peak value to the full-scale value of the converter.

The peak value detection is performed by reading white data from the sensor in the AGC mode selected from its three modes (AGC, UNIF and SCAN) of the M66335.

As shown in figure 4, preprocessing of peak value detection to increase the gain at the gain control is performed for a 8 line cycle and gain control processing to decrease the gain when the A/D converter over-flows is performed for another 8 line cycle after the start command (register 00: AGC) in the AGC mode.

As a result, the gain changes as shown in figure 5.



Figure 4 Peak Value Detection



Figure 5 Changes of the Gain in Peak Value Detection

Uniformity Correction

Uniformity correction is to correct shading distortion due to less light at each end of the light source and faded light around the lens, or high frequency distortion due to characteristic variations pixel by pixel in the image sensor.

As shown in figure 7, the M66335 makes blocks each of two pixels, creates a set of uniformity correction data for each block, and write them to the built-in correction memory (SRAM: 1024 word \times 6 bits) in the UNIF mode selected from its three modes (AGC, UNIF and SCAN).

The correction data created each for two pixels are read from the built-in correction memory to correct the input image data consecutively in the SCAN mode. With the register 01 (UNIFS) set at "1", the uniformity is not implemented.

With the register 02 (RES) set at "1", uniformity correction is performed on a block for 4 pixels.

For uniformity correction, white correction or the combination of black correction and white correction can be selected according to the types of image sensors as shown in table 4.

This is set in the register 00 (SENS, UMODE) and register 01 (UNIFM).

To perform both black correction and white correction, the black correction must be done first.

The M66335 implements the correction in the correction range of 50% as shown in figure 7. If a set of white correction data is beyond the correction range of 50%, the correction are not exactly performed as shown in figure 7. Therefore, ensure that input signals are within the range.



Figure 6 Waveform of White Data Output from the Image Sensor

Table 4	Uniformity	Correction	due to the	Image Sensor
---------	------------	------------	------------	---------------------

		Register								
Image Sensor	Correction	Type of the Sensor Register 00 (SENS)	Creation of Uniformity Correction Data Register 00 (UMODE)	Selection of Correction Mode Register 01 (UNIFM)						
CCD	White correction	0	1	0						
CIS	White correction	1	1	0						
	Black correction White correction	1	Period of black correction: 0 Period of white correction: 1	1						



Figure 7 Uniformity Correction

Resolution Change

Resolution change is controlled through H/W in the horizontal scanning direction and through S/W in the vertical scanning direction.

The sequence for resolution change is shown in figure 8.

Horizontal Scanning Direction

The scaling factor is written from the register 15 (CNV_D) to the built-in resolution change memory (100 W \times 1 bit) bit by bit by 100 operations.

MSSEL of the register 6 must be set at "0" (which specifies the horizontal scanning direction) before the scaling factor is written in the memory.

The procedure to specify CNV_D is as follows.

In the Case of Reduction

Data written in the resolution change memory have the following meaning.

"0": 1 pixel is output.

"1": No pixel is output.

(Example of reduction to 75%)

75 0's and 25 1's are written in the memory. The intervals of 1's should be as equal as possible to obtain the image with better quality.

In the Case of Enlargement

Data written in the resolution change memory have the following meaning.

"0": 1 pixel is output.

"1": 2 pixels are output.

(Example of enlargement to 150%)

50 0's and 50 1's are written in the memory. The intervals of 1's should be as equal as possible to obtain the image with better quality as in the reduction.

Vertical Scanning Direction

Processing of lines to implement the scaling factor in the vertical scanning direction is decided for each line through the register.

MSSEL of the register 6 must be set at "1" (which specifies the vertical scanning direction), and either "0" or "1" written in the register 15 (CNV_D) before the processing of each line.

The timing for this setting is in the period between the first transition of the INT signal (synchronized with that of ACCK) and that of the SH signal (the start of taking the SRDY signal in).

The procedure to specify CNV_D is as follows.

In the Case of Reduction

CNV_D indicates the current line read.

"0": 1 line of data are output.

"1": No line of data are output.

In the Case of Enlargement

CNV_D indicates the next line read.

"0": 1 line of data are output with PTIM generated (paper driven).

"1": 1 line of data are output with PTIM generated (paper not driven).

(Paper not driven: the same line is read again.)



Figure 8 Sequence of Resolution Change Setting

Use the PTIMB signal as control signals for the pulse motor for the reading roller. The sequence for reduction is shown in figure 9 and that for enlargement in figure 10.



1. At the initial setting, the enlargement/reduction setting (CNV_D) in horizontal scanning is implemented. Then, after the system is switched into the setting mode for enlargement/reduction in vertical scanning, the first line is set.

2. With a \downarrow flow of ACCK, the SCAN command is taken in, when the system comes into the standby mode for SRDYB. (START: H)

3. With a ↑ flow of SH, SRDYB: L is taken in, when scanning starts and PTIMB is output. (SSCAN: H)

4. During the period that STIMB is at L, converted binary data are output while the data for reduced lines are not output because STIMB for them are at H.

5. With a \uparrow flow of ACCK, SRDYB: H is taken in, when the reading of the single line is completed. (SSCAN: L)

6. With a \downarrow flow of SSCAN, INT is asserted. (INT: H)

7. With CPU ready for reading the next line, the enlargement/reduction setting (CNV_D) in vertical scanning is implemented; INTCLR is generated; INT is negated; and then SRDYB is set at L.

ACCK SH <SCAN> 1 2 (START) 5 <SRDYB> Enlarged (SSCAN) 3 Enlarged 6 line line INT STIMB SCLK SVID PTIMB <CNV D> 0 0 0 7 <INTCLR> : Output section <SCAN>, <SRDYB>, <CNV_D>, <INTCLR>: register setting (START), (SSCAN): internal signals 1. At the initial setting, the enlargement/reduction setting (CNV_D) in horizontal scanning is implemented. Then, after the system is switched into the setting mode for enlargement/reduction in vertical scanning, the first line is set. 2. With a \downarrow flow of ACCK, the SCAN command is taken in, when the system comes into the standby mode for SRDYB. (START: H) 3. With a \downarrow flow of SH, SRDYB: L is taken in, when scanning starts and PTIMB is output while it is not output for enlarged lines. (SSCAN: H) 4. During the period that STIMB is at L, converted binary data are output.

Figure 9 Reduction Processing Sequence

5. With a ↑ flow of ACCK, SRDYB: H is taken in, when the reading of the single line is completed. (SSCAN: L)

6. With a ↓ flow of SSCAN, INT is asserted. (INT: H)

7. With CPU ready for reading the next line, the enlargement/reduction setting (CNV_D) in vertical scanning is implemented; INTCLR is generated; INT is negated; and then SRDYB is set at L

Figure 10 Enlargement Processing Sequence

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MTF Compensation

As shown in figure 11, image data of characters or pictures photoelectrically converted by the sensor unit show degradation in resolution.

MTF compensation function of the M66335 restores the resolution of those data and expands the apparent dynamic range by strengthening the high-pass frequency constituent with the Laplacian filter.





γ Correction

 γ correction according to the sensitivity characteristics (logarithmic characteristics) of human eyes is implemented to approximate the image data to natural images.

To do this, the M66335 writes the γ correction table to the built-in SRAM and read the corrected values corresponding to read image data values from the SRAM.

 $\gamma = 0.45$ is considered to be the optimal for γ correction for thermal head printers. Figure 12 shows a characteristics example at $\gamma = 0.45$.

 γ correction processing is set through the register 06: GAMMA as follows.

GAMMA: 00 $\gamma = 1$ GAMMA: 01 $\gamma =$ conversion table valueGAMMA: 10 $\gamma = 1$ for image zone separation (character) $\gamma =$ conversion table value for image zone separation (photo)GAMMA: 11 $\gamma =$ conversion table value for image zone separation (character) $\gamma = 1$ for image zone separation (photo)

For the procedures of inputting/outputting of data, refer to the section on writing to/reading from the γ correction memory.



Background/Character Level Detection

The M66335 uses not the fixed threshold system but the floating threshold system, where the optimal threshold for simple conversion-to-binary of objective pixels are continually generated by constantly detecting background/character levels.

Accordingly, the threshold value proper for image data is generated without processing the data.

The threshold value is used for the areas to be converted to binary when simple conversion-to-binary or image zone separation is selected as the mode of conversion to binary in reading data.

: register 07 (MODE)

• Background level counter

When image data greater (lighter in light) than the current value are input, this counter counts up to approximate to the data.

When image data smaller (darker in light) than the current value are input, this counter counts down to approximate to the data.

- Setting of the rate of count-up/count-down following data input: register 0C (MAX_UP, MAX_DOWN)
- Setting of the lowest limit for background levels: register 0E (LL_MAX)
- Character level counter

When image data greater (lighter in light) than the current value are input, this counter counts up to approximate to the data.

When image data smaller (darker in light) than the current value are input, this counter counts down to approximate to the data.

- Setting of the rate of count-down following data input: register 0C (MIN_UP)

- Setting of the highest limit for character levels: register 0D (UL_MIN)



Figure 13 Background/Character Levels

Error Diffusion

The error diffusion, which is a conditional determination method, locally diffuses density errors between the original image and the result to obtain the best approximation. This generates images with good compatibility of gradation and resolution.

This is operated by selecting the error diffusion in conversion-into-binary mode selection.

: register 07 (MODE)

In error diffusion, dithers as well as density errors are added to image data. The dithers are data as commonly used for the dither matrix.

: register 08 (ERROR)

 $\boldsymbol{\gamma}$ correction must be performed in the error diffusion.

```
• Organized dither
```

The M66335 has built-in SRAM with a configuration of 64 words \times 6 bits for organized dither memory. In the initial setting, write the threshold value proper for the preferred dither pattern to the dither memory after setting the dither matrix size.

: register 07 (DITH)

: register 10 (DITH_D)

For the procedure of inputting/outputting data, refer to the section on writing to/reading from the dither memory.



Figure 14 Error Diffusion Method

Image Zone Separation

To make data conversion fit for each image zone, a black and white image is separated into the zones to be converted to binary and the gradation zones. The binary zone is processed through simple conversion to binary and the gradation zone through the error diffusion.

: register 08 to 0E

In the black and white image, each window of the With this characteristic of the gradation zone, it is	e gradation zone (photo) does not have a large distinguished from the conversion-into-binary	e difference of luminance in it. v zone through the following method.
L	.max: maximum illumination in window .min: minimum illumination in window	
Determining inequality 1: Lmax – Lmin > A (beca a larg Determining inequality 2: Lmin > B (for th Determining inequality 3: Lmax < C (for t If the window satisfies determination ineq If the window does not satisfy any of determination	use the zone to be converted to binary has ge difference in luminance in it.): register 09 D le wholly white area): register 0A M he wholly black area): register 0B M ualities 1, 2 or 3, simple conversion to binary in rmination inequalities 1, 2 and 3, change to participate	ifference (SEPA_A) linimum (SEPA_B) laximum (SEPA_C) is applied. seudo-halftone is applied.
White level = 63 Difference	Minimum	Maximum
Input data Lmin $$	В	C Lmax

Figure 15 Image Zone Separation

Region Designation Function

The sensor width is fixed for A4 and B4.

The region designation function is to output only the data for a region defined and designated in terms of output data after resolution change (or after uniformity correction for multivalued data).

Registers 11 to 14 (OFFSET, OUTLENGTH)



Figure 16 Cut-out Function

(4) CODEC Interface (Binary Data Output)

Serial Output



Parallel Output



(5) DMA Interface (Multivalued Output)

The DMA transfer of data after non-uniformity correction can be performed by setting P_O) of the register 01: at "1" (existence of DMA output) and M_B of that register at "1" (multivalue). With this setting, neither enlargement, nor reduction, nor 400 dpi of resolution can be set.



- 1. On completion of reading one line, with a \downarrow flow of SSCAN, the reset signal is entered in the DMA counter.
- 2. With a \uparrow flow of the reset signal, DRQ shifts to "H", when the DMA transfer becomes ready.
- 3. With DAKB at "L" and a ↓ flow of RDB, DRQ shifts to "L", when multivalued data are output to D <7:2> during the period that RDB is at "L".
- 4. With a ↑ flow of DAKB, the DMA counter counts up and DRQ shifts to "H", when the DMA transfer becomes ready again.
- 5. The cycle of the above 3 and 4 is repeated until the DMA counter counts up to reach the number of output pixels set in the registers 13 and 14 OUTLENGTH subtracted by one. By that repetitive operation, DMAFIN shifts to "H" to terminate the DMA transfer when it reaches the set number.
- 6. With a \downarrow flow of DMAFIN, INT shifts to "H", when CPU has an interrupt.
- 7. Reading is resumed from the next line by negating the INT signal through the register 17 (INTCLR).

(6) Writing to/Reading from the Dither Memory, γ Correction Memory, Uniformity Correction Memory, and Resolution Change Memory

The sequences of writing a dither pattern to and reading it from SRAM with a configuration of 64 words \times 6 bits which is built in the M66335 for organized dither are shown below.



- 1. D6 and D5 (DITH) of the register 07 are set to define the dither matrix size.
- 2. D0 (CNTRST) of the register 01 is set at "1" to reset the address counter of the dither memory.
- 3. DITH_D is selected in the register 10, and DATA (0) of the MPU bus (D5 to D0) is written in the memory. The address counter of the dither memory is incremented at the edge of the first transition of WR. (For writing)
- 4. DITH_D is selected in the register 10, and DATA (0) of the dither memory is read into the MPU bus (D5 to D0). The address counter of the dither memory is incremented at the edge of the first transition of RD. (For reading)

	4 × 8 I	Matrix						8 × 8	Matrix			
A28	A29	A30	A31		A56	A57	A58	A59	A60	A61	A62	A63
A24	A25	A26	A27		A48	A49	A50	A51	A52	A53	A54	A55
A20	A21	A22	A23		A40	A41	A42	A43	A44	A45	A46	A47
A16	A17	A18	A19	1	A32	A33	A34	A35	A36	A37	A38	A39
A12	A13	A14	A15		A24	A25	A26	A27	A28	A29	A30	A31
A8	A9	A10	A11		A16	A17	A18	A19	A20	A21	A22	A23
A4	A5	A6	A7		A8	A9	A10	A11	A12	A13	A14	A15
A0	A1	A2	A3		A0	A1	A2	A3	A4	A5	A6	A7

Dither Matrix Addresses

A12 A13 A14 A15							
A10	A10	A 1 4	A 1 5				
A8	A9	A10	A11				
A4	A5	A6	A7				
A0	A1	A2	A3				

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The sequences of writing γ correction table to and reading it from SRAM with a configuration of 64 words × 6 bits which is built in the M66335 for γ correction are shown below.



- 1. D0 (CNTRST) of the register 01 is set at "1" to reset the address counter of the γ correction memory.
- GAMMA_D is selected in the register 0F, and DATA (0) of the MPU bus (D5 to D0) is written in the memory. The address counter of the γ correction memory is incremented at the edge of the first transition of WRB. (For writing)
 GAMMA_D is selected in the register 0F, and DATA (0) of the γ correction memory is read into the MPU bus (D5
- to D0). The address counter of the γ correction memory is incremented at the edge of the first transition of RDB. (For reading)

Uniformity correction data can be written to and read from SRAM for uniformity correction built in the M66335 through the MPU bus. With this operation, the uniformity data can be temporarily saved in the backup memory when the power is off. The sequences of writing and reading uniformity correction data are shown below.



- 1. "0" (black correction) or "1" (white correction) is set in D1 (Umode) of the register 00.
- 2. D0 (CNTRST) of the register 01 is set at "1" to reset the address counter of the uniformity correction memory.
- 3. UNIF_D is selected in the register 19, and DATA (0) of the MPU bus (D5 to D0) is written in the memory. The address counter of the uniformity correction memory is incremented at the edge of the first transition of WRB. (For writing)
- 4. UNIF_D is selected in the register 19, and DATA (0) of the uniformity correction memory is read into the MPU bus (D5 to D0). The address counter of the uniformity correction memory is incremented at the edge of the first transition of RDB. (For reading)

The sequences of writing a resolution change table to and reading it from SRAM with a configuration of 100 words \times 1 bit which is built in the M66335 for resolution change are shown below.

Writing to the resolution cha	ange memory (MPU $ ightarrow$ N	/66335)		
	Initial setting (1)	Initial setting (2)	Memory address (0)	Memory address (1)
CSB				
A4 to A0	06Н Х	01H	X 15H	15H
WRB				
D7 to D0 (Input)	{D7 = "0"}	(D0 = "1")2	(DATA (0)) 3	(DATA (1))
Reading from the resolutior	n change memory (M663	$335 \rightarrow MPU)$	•	· · ·
	Initial setting (1)	Initial setting (2)	Memory address (0)	Memory address (1)
CSB				
A4 to A0	06Н	01H	X 15H	15H
WRB			1 	
D7 to D0 (Input)	(D7 = "0")	(D0 = "1")		
RDB				
D7 to D0 (Output)			(DATA (0))	(DATA (1))
	1	2	4	4

- 1. "0" (horizontal scan) is set in D7 (MSSEL) of the register 06.
- 2. D0 (CNTRST) of the register 01 is set at "1" to reset the address counter of the resolution change memory.
- 3. CNV_D is selected in the register 15, and DATA (0) of the MPU bus (D0) is written in the memory. The address counter of the resolution change memory is incremented at the edge of the first transition of WRB. (For writing)
- 4. CNV_D is selected in the register 15, and DATA (0) of the resolution change memory is read into the MPU bus (D0). The address counter of the resolution change memory is incremented at the edge of the first transition of RDB. (For reading)

List of the M66335FP Registers

R/W	A4 to A0	Default	D7	D6	D5 D4 D3 D2 D1					D0
R/W	00H	00H	RESET	SENS	SENS_W	AGC	UNIF	SCAN	UMODE	"L"
R/W	01H	00H	SOURCE	S/H_W	SH_W	UNIFS	P_O	M_B	UNIFM	CNTRST
W	02H	00H	RES	LCMPS	BLS	BLCMPS	CCD	CIS3	CIS2	CIS1
W	03H	00H				PRE_DA	ATA (7:0)			
W	04H	00H					PRE_DA	TA (13:8)		
W	05H	00H				ST_P	L (7:0)			
W	06H	00H	MSSEL	AVE	CONV	< <1:0>	CONV	Y <1:0>	GAMM	A <1:0>
W	07H	00H	POL	DITH	<1:0>	MODE	<1:0>		SLICE <2:0>	
W	08H	00H			ERROF	R <1:0>	MTF_C	C <1:0>	MTF_I	<1:0>
W	09H	00H					SEPA_	A (5:0)		
W	0AH	00H					SEPA_	B (5:0)		
W	0BH	00H					SEPA_	C (5:0)		
W	0CH	00H			MAX_U	P <1:0>	MAX_DO	WN <1:0>	MIN_U	P <1:0>
W	0DH	1FH					UL_MI	N <5:0>		
W	0EH	20H					LL_MA	X <5:0>		
R/W	0FH	—					GAMMA	_D (5:0)		
R/W	10H	—					DITH_	D (5:0)		
W	11H	00H				OFFSE	T <7:0>			
W	12H	00H					0	FFSET <12:8	}>	
W	13H	00H				OUTLENC	GTH <7:0>			
W	14H	00H					OUT	LENGTH <1	2:8>	
W	15H	_								CNV_D
R/W	16H	00H						AGCSTP	SRDYS	SRDYB
W	17H	_				INT	CLR			
R/W	18H	00H				GAIN	<7:0>			
R/W	19H	00H					UNIF_[D <5:0>		

Register Structure

Address	R/W	Description										
00 _H	R/W	D7	D6	D5	D4	D3	D2	D1	D0			
		RESET	SENS SENS_W AGC UNIF				SCAN	UMODE	"L"	(Default value: 00 _H)		
		D7	RE	ESET: Sys	tem Rese	et	Wi	th D7 = 1, t	he syste	em is reset during the		
		0	Normal mo	ode			pe	riod that the	e write p	oulse is "L".		
		1	Reset mod	de			(*)	Write only				
							_					
		D6	S	ENS: Sen	sor Type	9						
		0	CCD									
		1	CIS: (75%	of clock d	uty)							
		D5	SENS_W	: Reading	Width of	the Sens	or					
		0	A4									
		1	B4									
		D4		AGC: AG	C Mode		Co	ontrols start/	stop of	the AGC mode.		
		0	Stop									
		1	Start									
		D3		UNIF: UN	IF Mode		Controls start/stop of the UNIF mode.					
		0	Stop									
		1	Start									
		D2	S	SCAN: SC	AN Mode		Co	ontrols start/	stop of	the SCAN mode.		
		0	Stop									
		1	Start									
			l	UMODE: L	Jniformit	y Correcti	on in the	e UNIF Mod	le			
		D1	Black Co	orrection -	+ White C	orrection	Or	nly White C	orrecti	on		
		0	Black corre	ection								
		1	white corr	ection			vvnit	e correctior	1			
01 _H	R/W											
				D5	D4	D3	D2	D1	D0			
		SOUR	JE S/H_W	5/H_W	UNIFS	P_0	M_B	UNIFM	CNIRS	(Default value: 00H)		
								-				
		D7	SOUR	CE: Read	ing Width	n of the O	riginal	_				
		0	A4					_				
			D4									
		D 0		0.00	0.01/ 5 -			-				
		D6	Normal	S/H_W:	5/W Puls	e Width	vala)	-				
		U 1	Normal r			ITI CIOCK C)	rcie)					
			TNOIMAIT		y 0.5							

Address	R/W					De	escrip	lion
01 _H	R/W	D5		CH W.		Width]
		0	Normal (1	6 times t	the syste	m clock cvc	le)	-
		1	Reverse	of norma	l multiplie	ed by 2	(0)	
		·	11010100	ornonna	manipire			
		D4		S. Unifo	rmity Co	rrection		
		0	Valid	0. 00				
		1	Invalid					
		D3		P_0: D	MA Outp	ut		00 is output in the form of LSB and D7 in the
		0	Without D	DMA outp	out		fo	orm of MSB.
		1	With DM	A output				
		D2	M	_B: Proc	essing I	Node	V	Vith the multivalue selected, data (6-bit) after
		0	Binary				n +	onuniformity correction can be output through
		1	Multivalue	e				
								_
		D1	UNIF:	Uniformi	ty Corre	ction in SC	AN	
		0	White cor	rection				-
		1	Black cor	rection +	white co	rrection		
		DO	CNTRS	ST: Addro	ess Cour	nter Reset		vith D0 = 1, the counter is reset during the period that the write pulse is "I "
		0	Normal II				- A	It he built-in RAM addresses are reset.
		- 1	neset inc	Jue			(*	*) Write only
02 _H	W	DZ	De	D5	D/	1 D3	г	
		RES		S BLS	BLCN	PS CCD		IS3 CIS2 CIS1 (Default value: 00µ)
			_		_			
		D7	BE	S: Reso	lution		D6	LCMPS: Line Clamping
		0	200 dpi				0	Invalid
		1	400 dpi				1	Valid
		<u> </u>				<u> </u>		
		D5	BL	S: Bit Cla	amping		D4	BLCMPS: Black Level Line Clamping
		0	Invalid				0	Invalid
		1	Valid				1	Valid
		D3	D2	D1	D0	Senso	rs Co	mpatible with Image Sensor Interfaces
		0	0	0	1	CIS1: ser	isors w	vith the input level of 2 V or higher
		0	0	1	0	CIS2: ser	isors w	vith the input level of under 2 V
		0	1	0	0	CIS3: ser	isors c	apable of line clamping
		1	0	0	0	CCD		

03 _H W D7 D6 D5 D4 D3 D2 D1 D0									
PBF_DATA <7:0> (Defa	ault value: 00⊾)								
$D7$ to D0: PRE_DATA <7:0> the lowest order 8 bits of the single-line cycle counter y									
04 _H W D7 D6 D5 D4 D3 D2 D1 D0									
PRE_DATA <13:8> (Defa	ault value: 00 _H)								
D5 to D0: PRE_DATA <13:8> the highest order 6 bits of the single-line cycle counter	er value								
05 _H W D7 D6 D5 D4 D3 D2 D1 D0									
ST_PL <7:0> (Defa	ault value: 00 _H)								
D7 to D0: ST PL <7:0> start pulse position to the sensor									
Set $ST_PL = (dummy pixels of the sensor + 2)$.									
D7 D6 D5 D4 D3 D2 D1 D0									
MSSEL AVE CONVX CONVY GAMMA (Defa	ault value: 00 _H)								
D7 MSSEL: Horizontal and Vertical Setting									
0 Horizontal									
1 Vertical									
D6 AVE: Averaging Processing When "with averaging" selected:									
0 With averaging For enlargement: inserted lines are the	average of the								
1 Without averaging For reduction: the subsequent lines from	m removed lines								
are the average of the re-	emoved one and								
the current one.									
CONVX: Enlargement/Reduction Mode RES = 1									
D5 D4 in the Horizontal Scanning Direction With the setting	ng of 400 dpi,								
0 0 Original scale enlargement ca	cannot be set.								
0 1 Enlargement									
CONV/V: Enlargement/Deduction Mode									
D3 D2 in the Horizontal Scanning Direction									
0 0 Original scale									
0 1 Enlargement									
1 0 Reduction									

Address	R/W		Description												
06 _H	W	D1	D0		GAMMA	Correcti	on Proc	essina]					
		0	0	Character	photo: $\gamma = 1$	1		essing							
		0	1	Character	$\gamma = 0$	download	value								
		1	0	Character	$\gamma = 1$: photo: $\gamma = 1$										
		1	1	Character	$\gamma = downlo$	ad value:	photo: v	= 1							
		Noto: lu	Idamont	botwoon of	aractor and	nhoto is k	protor /	the recult (fimago	J zono conoration					
		Note. Ju	lagment	between ci	leen character and photo is based on the result of image zone separation.										
07 _H	W	D7	De	D5	D4	50	נח	D1	DO						
		POL			MO		DZ	SUCE	DU	(Default value: (00)				
		TOL		DIIII	WO		(он)								
		D7	POL:	Conversio	n-to-Binary	Output M	lode								
		0	White: 7	l; black: 0											
		1	White: (); black: 1											
		D6	D5	DIT	H: Dither M	atrix Size)]							
		0	0	4 × 4											
		0	1	4 × 8											
		1	0	8 × 8											
		1	1	_											
								-							
		D4	D 2	MODE	Coloction of	the Con		to Dinama		1					
		04	03	Simple bi		the Con	version	-to-Binary I	vioae						
		0	1		laiy 1 dithor										
		1	0	Image zo	ne senaratio	n (simple	hinarv +	error diffusi	on)						
		1	1	Error diffu	sion	(0		0.101 0.1100	•,						
		· ·			0.011]					
		D2	D1	D0	SLICE	: Thresh	old Fact	tor for Conv	ersion/	to Binary					
		0	0	0	6/16										
		0	0	1	7/16										
		0	1	0	8/16										
		0	1	1	9/16										
		1	0	0	10/16										
		1	0	1	11/16										
		1	1	0	12/16										
		1	1	1	13/16										

Address	R/W					Des	cription			
08 _H	W	D7	De	DE	D4	20	20	D1	DO	
				FR	BOB	MT	= C	МТ	= 1	(Default value: 00 ₄)
						, ivi i	_0		_'	
										-
						ERRC	R			-
		D5	D4	Error (E	lase)	Rate of	Dither Ad	dition to E	rrors	-
		0	0	Strong (7/8	s)	Weak (1/8	3)			-
		0	1	Strong (7/8	5)	-				
		1	0	Weak (3/4)	Weak (3/4) Weak (1/8)					-
		1	1	Weak (3/4)						
		D3	D2	MTF C: N	TF Com	pensation	Factor			
		0	0	1/4						
		0	1	1/2						
		1	0	1						
		1	1	0						
		Note: Th	nis is vali	d when MOI	DE is sim	ple binary o	or image z	zone separa	ation (cl	naracter).
		D1	DO		TE Comr	onestion	Factor			
			0	1/4			actor			
		0	1	1/2						
		1	0	1						
		1	1	0						
		Note: Th	nis is vali	d when MOI	DE is ora	anized dithe	er error d	liffusion or i	image z	one separation (photo)
		Note. II	15 15 Val						mage z	one separation (photo).
09 _H	W									
			D6	D5	D4	D3	D2	D1	D0	
						SEP	A_A			(Default value: 00 _H)
		D5 to D0): SEPA_	_A Image zo	one sepa	ration parai	neter (dif	ferential)		
0A _H	W	D7	DA	Dr	D4	Da	Do	Dí	Da	
				D5	D4	D3	D2	D1	D0	
						SEP	А_В			(Default value: 00 _H)
		D5 to D0): SEPA	_B Image zo	one sepa	ration parai	neter (mi	nimum)		
0B _H	W	D7	De			50	¢٦	D1	DO	
				00	D4		A C	וט	00	(Default value: 00)
				C Imaria =		JLF				
		D5 to D(J: SEPA	_o image z	one sepa	ration para	meter (ma	aximum)		

Address	R/W		Description											
0C _H	W	D7	De	DE	D4	50	DO	1	DO					
				D5						(Default value: 00.)				
					X_UP				UP					
		D5	D4	MAX_UF	: Backgro	und Leve	I Detectio	n Clock fo	or the l	Up Counter				
		0	0	Ordinary (T = (single	pixel cycle	e) × 32)							
		0	1	Slow (T =	(single pixe	el cycle) \times	64)							
		1	0	Fast (T = (single pixe	el cycle) × ⁻	16)							
		1	1	Fastest (T	= (single p	oixel cycle)	× 8)							
		D3	D2		AX DOWN: Background Level Detection Clock for the Down Counter									
		0	0	Ordinary (rdinary (T = (single nivel cycle) > 128)									
		0	1	Slow (T =	$(T - (single pixel cycle) \times 256)$									
		1	0	Fast (T = $($	sinale pixe	el cvcle) × (<u> </u>							
		1	1	Fastest (T	stest (T = (single pixel cycle) \times 32)									
				, , , , , , , , , , , , , , , , , , ,		<u>,</u>	,							
		D1	D0	MIN_U	P: Charac	ter Level	Detection	Clock for	the Up	o Counter				
		0	0	Ordinary (T = (single	pixel cycle	e) × 128)							
		0	1	Slow (T =	(single pixe	el cycle) ×	256)							
		1	0	Fast (I = (single pixe	$(cycle) \times 0$	64)							
		1	1	Fastest (I	= (single p	ixel cycle)	× 32)							
0D _H	vv	D7	D6	D5	D4	D3	D2	D1	D0					
			/	/		UL_	MIN			(Default value: $1F_H$)				
		D5 to D0): UL_M	IN Detectio	n of backg	round/chai	racter leve	ls						
				Highest	limit of cha	aracter leve	els							
	\M/													
ΟĽΗ	**	D7	D6	D5	D4	D3	D2	D1	D0	_				
						LL_I	XAN			(Default value: 20_H)				
		D5 to D0): LL_M	AX Detectio	n of backg	round/cha	racter leve	els						
				Lowest I	imit of bac	kground le	vels							
		Lowest I	imit of b	ackground le	evels (LL_I	MAX) > hig	ghest limit	of characte	er levels	s (UL_MIN)				
0F _H	R/W	67	Da		D4	Da	Da	Di	Da					
				D5	D4		D 25:0	D1	D0					
							_D < 0.0>							
		D5 to D0): GAMIN	IA_D Built-	in γ memoi	'y data								
10 _Н	R/W	D7	De	DS	D4	٤U	D2	D1	DO					
				00	04) <5:0>		20	7				
			ע יידוח יי		lithor mom	onu data								
		00 00 00	חווט. <i>י</i> H_	ם סטוונ-ווז ס		ory uata								

Address	R/W					Des	cription					
11 _H	W	D7	D6	D5	D4	D3	D2	D1	D0			
					OFFSE	T <7:0>				(Default value: 00 _H)		
		D7 to D0:	07 to D0: OFFSET <7:0> Offset for cut-out Lowest order 8 bits									
12 _H	W	D7	D6	D5	D4	D3	D2	D1	D0			
			OFFSET <12:8> (Default value: 00 _H)									
		D3 to D0:	03 to D0: OFFSET <12:8> Offset for cut-out Highest order 5 bits									
13 _H	W	D7	D6	D5	D4	D3	D2	D1	D0	-		
			OUTLENGTH <7:0> (Default value: 00 _H)									
		D7 to D0:	OUTLEN	GTH <7:0	> No. of o	utput pixe	ls Lowest	order 8 k	oits			
14 _H	W	D7	D6	D5	D4	D3	D2	D1	D0			
						OUTI	ENGTH <	12:8>		(Default value: 00 _H)		
		D3 to D0: OUTLENGTH <12:8> No. of output pixels Highest order 5 bits Note: OUTLENGTH <12:8> must be a multiple of 8. If a number of output pixels is not a multiple of 8, the remainder of the division must be omitted.										
15 _н	R/W	07	Da	DE	D4	Do	Do		Da			
				5	D4					7		
									CNV_D			
		D0: CNV_	D Indicati	on of enl	argement/	reduction						

Address	R/W	Description										
16 _H	R/W	D7	De	DE	D4	2	D2	D1	DO			
							AGCSTP	SBDVS	SBDVB	(Default value: 00)		
							Adoon	011010	SILUTE	(Delault Value. 00H)		
		D2	AGCST	P: Gain C	ontrol Co	ounter						
		0 0	ain contro	ol counter	valid.							
		1 0	ain fixed.									
		D1	SRI	DYS: SRE	Y Contro	bl						
		0 S	RDY cont	trol throug	h the regi	ster						
		1 S	RDY cont	trol throug	h the exte	ernal pin						
		D0 \$	SRDYB: D	Data Tran	sfer Star	t Ready	In t	he case c	of data con	trol through the		
		0 T	ransfer al	lowed.		· · · · ,	reg	ister, the	SDRYB in	put pin must be		
		1 T	ransfer no	ot allowed			alw	ays set a	t "H".			
		L.	For the control through the re									
			SRUY register must be controlled line by									
			IINE. (*) Write only									
17 _H	W						())			
		D7	D6	D5	D4	D3	D2	D1	D0			
					INT	CLR						
		INT signal	s are neg	ated by a	ccessing t	o this add	ress.					
18 _H	R/W	57	5.0	55	54	50	Da	D /	50			
			D6	D5		D3	D2	D1	DU			
					GAIN							
		In reading	the curre	ent gain v	alue of the	e gain con	trol counter	r can be r	ead.			
		in writing.	Howeve	value of t	ne gain c alid only i		$\frac{1}{2} = 1$	sel.				
			11000606	1, 1113 13 V	and only i	I AUUUII	- 1.					
19 _H	R/W	D7	D6	D5	D4	D3	D2	D1	D0	With UMODE = 0.		
						UNIF	<5:0>			access to the		
		D5 to D0.		Built- in u	niformity o	orrection	memory da	ta		uniformity correction		
		memory for black										
			With UMODE = 1,									
										uniformity correction		
										memory for white		
										correction is available.		

Description of the Operations of the Analog Circuits

The configuration of the analog processing circuits is shown in figure 17.

(1) Sensor Selection Circuit

The four types of sensors in the table can be connected to the circuit.

Register 02 _H		Sensor Type					
CCD	CCD sensor						
CIS1	CIS sensor which out	puts light voltages (white voltage) of 3.5 V or lower					
CIS2	CIS sensor which outputs light voltages (white voltage) of 2 V or lower						
CIS3	CIS sensor which output shielding pixels for each line						
<ccd mode=""> Black Max 500 mVp-p White Blanking element Shielding pixel part</ccd>	Signaling element	The amplitudes of sensor signals are multiplied by -4 through the two operating amplifiers directly after the switch to select the CCD mode. (The waveforms of the signals are inverted at the same time.) As a result, the sensor signals input to the sample and hold circuit have a dark voltage of 2.2 V.					
<cis1 mode=""> White Max 3.5 V Black ±200 mV</cis1>	←→ Signaling element	The amplitude of signals input from the sensor are halved. Then, their reference potential is shifted up to 2.2 V. As a result, the sensor signals input to the sample and hold circuit have a dark voltage of 2.2 V.					
<cis2 mode=""> White Max 2 V Black ±200 mV</cis2>	→ ^{Signaling element}	The reference potential of signals input from the sensor is shifted up to 2.2 V. As a result, the sensor signals input to the sample and hold circuit have a dark voltage of 2.2 V.					
<cis3 mode=""> White 2 Vp-p Black Clamping level Shielding pixel part</cis3>	Signaling element	Sensor signals with a dark voltage of 2.2 V clamped by line clamping input are directly input to the sample and hold circuit.					

(2) Line Clamping Circuit

This circuit is used for CCD (line clamping mode) and CIS3.

The reference voltage (dark voltage) output in the shielding pixel part of the sensor is sampled by LCMP (line clamping pulses) and shifted up to the internal reference voltage of 2.2 V. This is not used for the CIS1 or CIS2 input sensor (set off constantly).

: register 02 (LCMPS)

(3) Sample and Hold Circuit and Bit Clamping Circuit

In the CCD mode, bit clamping, as well as line clamping, can be performed. The blanking elements of each pixel of sensor output is sampled by BTCMP (bit clamping pulses). The differences of signals from the reference potential sampled by the bit clamping circuit are input to the gain control circuit of next step as signaling elements. To turn off bit clamping, set BLS invalid, so that the reference potential will be fixed at the internal reference potential of 2.2 V.

: register 02 (BLS)

(4) Gain Control Circuit

The amplifying factor (gain) must be adjusted so that the amplitudes of sensor signals can come within the dynamic range of the A/D converter. The gain is set through the automatic gain control in the AGC mode (register 00) or directly through the register 18 (GAIN <7:0>).

The gain changes within the following ranges according to the sensor used.

Mode	Amplifying Factor of Signals (Gain)
CCD	4 to 20
CIS1	0.5 to 2.5
CIS2	1 to 5
CIS3	1 to 5

In the AGC mode, the gain control counter is set at the greatest gain in the initial state and then counted down each time an overflow bit is output from the A/D converter. The count (gain) of the gain control counter is directly read/written through the register 18 (GAIN <7:0>). The counting operation of the counter can be controlled through the register 16 (AGCSTP).

(5) Internal Reference Voltage

Internal reference voltage source for the analog circuits:

this generates the reference voltage (2.2 V) for the line clamping circuit, the sample and hold circuit, and the bit clamping circuit.

A/D converter reference voltage generation circuit:

this generates VWL (white level reference voltage of 3.8 V) and VBL (black level reference voltage of 1.8 V) for the A/D converter.

(6) Black Level Clamping Circuit

This circuit adjust the level of reference voltage to the A/D converter from analog circuits.

The black clamping circuit is used in the CCD or CID3 mode. (See figure 18, 19 and 22) The GCAO pin and the BCMI pin are capacity-coupled. The output reference potential in the shielding pixel part of sensor signals are applied to the BCMV pin as the VBL (black level reference voltage of 1.8 V) for the A/D converter.

BLCMP (black level clamping pulses) are generated concurrently with the shielding pixel part of each line. To turn off this circuit, set BLCMPS invalid and apply the black level reference voltage of the A/D converter to the BCMV pin.

: register 02 (BLCMPS)

In the CIS1 or CIS2 mode, the LEVAJ pin is used. (See figure 20 and 21) Voltage is applied to the LEVAJ pin so that the reference potential of output at the GCAO pin can be adjusted to the VBL (black level reference voltage of 1.8 V) of the A/D converter. Set voltage input to the LEVAJ pin as follows.

$$VLEVAJ = VVBL - A \times G_V + 0.2 [V]$$

$$VGCAO = VLEVAJ + G_V \times V_{IN} [V]$$

where,

- A: the lowest limit of dark voltage of the sensor [V]
- G_V : gain (multiplying factor) of the gain control circuit

 V_{IN} : signals input from the sensor [V]

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Vcc

Digital circuit

GND

LCMP

S/H

BLS

BTCMP

BLCMP

RESET

ADCK GAIN <7:0>

OF

DIN <6:0>

MCIS <3:1>, MCCD

BCMI BCMO

ø

E

Black level

clamping circuit

AGCSEL <7:0>

Vref+

OF

B <7:1>

W IF

DVcc

DGND

RENESAS

Analog Circuit Timing Chart (for CCD Mode/Bit Clamping)

Register	Address	00H	02H							
	Bit	D6	D6	D5	D4	D3	D2	D1	D0	
Mode	Signal	SENS	LCMPS	BLS	BLCMPS	CCD	CIS3	CIS2	CIS1	
CCD (bit clamping)	Setting	1	1	1	1	1	0	0	0	



Analog Circuit Timing	Chart (for CCD	Mode/Line Clamping)
------------------------------	----------------	---------------------

Register	Address	00H	02H							
	Bit	D6	D6	D5	D4	D3	D2	D1	D0	
Mode	Signal	SENS	LCMPS	BLS	BLCMPS	CCD	CIS3	CIS2	CIS1	
CCD (line clamping)	Setting	1	1	0	1	1	0	0	0	





Analog Circuit Timing Chart (for CIS1 Mode)



Analog Circuit Timing Chart (for CIS2 Mode)

Register Address 00H 02H Bit D6 D6 D5 D4 D3 D2 D1 D0 Mode Signal SENS LCMPS BLS BLCMPS CCD CIS3 CIS2 CIS1 CIS3 Setting 0 1 1 0 1 0 1 0 Shielding pixel part Effective pixel part Non-signaling part SH CK1 CIS signal output LCMP BTCMP = "H' S/H J Л Л U GCAO signal output BLCMP BCMO signal output A/D clock A/D output Unit: 1/SYSCK Non-signaling part Shielding pixel part Effective pixel part SH 16 CK1 16 CIS 10 2 4 Ν signal output LCMP 1 BTCMP = "H" 16 7 S/H 1 4 i GCAO Ν signal output 8 8 _ BLCMP BCMO Ν signal output A/D clock

Analog Circuit Timing Chart (for CIS3 Mode)

A/D output

X

Ν









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Flowchart

Reading Operations (for the CCD Sensor)



Reading Operations (for the CIS Sensor)



MPU Interface

Timing for Read Operation (M66335 \rightarrow MPU)



Timing for Write Operation (MPU \rightarrow M66335)



DMA Timing

Timing for Read Operation (M66335 \rightarrow System Bus)



Timing of CODEC



Cautions for Use

(1) Access to Address 00h

To gain access to address 00h, the value of built-in GCC (gain control counter) may be set to FFh.

This requires to read GAIN value at address 18h before access to address 00h and write the GAIN value at address 18h after the access (see flowchart A).



Flowchart A Address 00h Access Flow

(2) Reset

The M66335FP adopts the two types of reset. These reset functions are provided in table A.

Table A Reset Functions

Function	Register	Internal F/F	GCC
Reset Type	Initialization	Initialization	Initialization
Hardware reset (RESET)	0	0	0
Software reset register 0 (RESET)		0	0

Package Dimensions



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